IN THE CLAIMS:

Please amend claim 5 and cancel claim 10 without prejudice or disclaimer. This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

Claims 1-4 (canceled).

Claim 5 (Currently Amended): A multilayer printed wiring board comprising:

a substrate;

a plated through-hole formed in the substrate;

a solvent-free insulative filling material filled in the plated through-hole;

a conductor layer plated on an exposed surface of the solvent-free insulative filling material;

an insulating layer formed on a surface of the conductor layer;

a conductive pattern layer formed on a surface of the insulating layer; and

a via conductor connecting the conductor layer and the conducting pattern layer;

wherein the solvent-free insulative filling material includes a filler, a thermosetting epoxy resin, a curing catalyst and a dicyandiamide curing agent, [[and]]

wherein the dicyandiamide curing agent is used to reduce deterioration in adhesive strength between the solvent-free insulative filling material and the conductor layer, and

wherein the curing catalyst comprises a urea compound.

Claim 6 (Previously Presented): The multilayer printed wiring board according to claim 5, wherein the conductor layer, the insulating layer and conductor pattern layer are provided in this order.

Claim 7 (Original): The multilayer printed wiring board according to claim 5, wherein the plated through-hole has a diameter of 200 μm or smaller.

Claims 8-10 (Canceled).

Claim 11 (Previously Presented): The multilayer printed wiring board according to claim 10, wherein the urea compound is a material selected from the group consisting of dimethylurea compound, aromatic urea compound, alicyclic urea compound and halogenated urea compound.

Claim 12 (Previously Presented): The multilayer printed wiring board according to claim 10, wherein the urea compound is a material selected from the group consisting of dimethylurea compound, aromatic urea compound and alicyclic urea compound.

Claim 13 (Previously Presented): The multilayer printed wiring board according to claim 5, wherein the dicyandiamide curing agent has at least one form selected from the group consisting of powders, dendrites, and flakes.

Claim 14 (Previously Presented): The multilayer printed wiring board according to claim 13, wherein the dicyandiamide curing agent is powder having an average particle size of 0.1 to 100 μm.

Claim 15 (Previously Presented): The multilayer printed wiring board according to claim 13, wherein the dicyandiamide curing agent is powder having an average particle size of 1 to 30 μm.

Claim 16 (Previously Presented): The multilayer printed wiring board according to claim 13, wherein the dicyandiamide curing agent is powder having an average particle size of 1 to 15 μm.

Claim 17 (Previously Presented): The multilayer printed wiring board according to claim 5, wherein the filler is substantially spherical particles having an average particle size of 0.1 to 12 μm and a maximum particle size of 75 μm or smaller.